ABSTRACT

WIRE PATH PLATE HAVING ENHANCED DURABILITY FOR WIRE BONDING

A wire path plate for a wire bonding apparatus includes a first conductive plate coupled to a second conductive plate. Each conductive plate has an upper portion, a lower portion and a middle portion located between the upper and lower portions. A bonding wire is configured to be passed through a gap formed between the first and second conductive plates. At least one non-conductive strip is mounted along the upper and/or lower portions of at least one of the conductive plates for insulating the bonding wire from conductive surfaces of the at least one conductive plate at the position of the at least one non-conductive strip.

(FIG. 6)